Reliability-Configurable Mixed-Grained Reconfigurable Array Compatible with High-Level Synthesis

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1S-7 Background

NRE cost is elevating as VLSI technology advances.

• Reconfigurable VLSIs are widely used to save cost.

Guaranteeing reliability of information systems becomes a societal requirement.



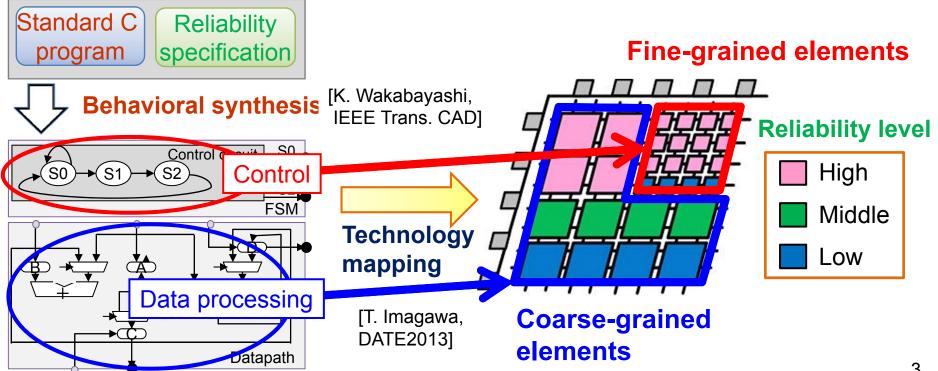
Reliability of reconfigurable VLSIs is drawing much attention

 especially from mission critical applications such as space and medical ones.

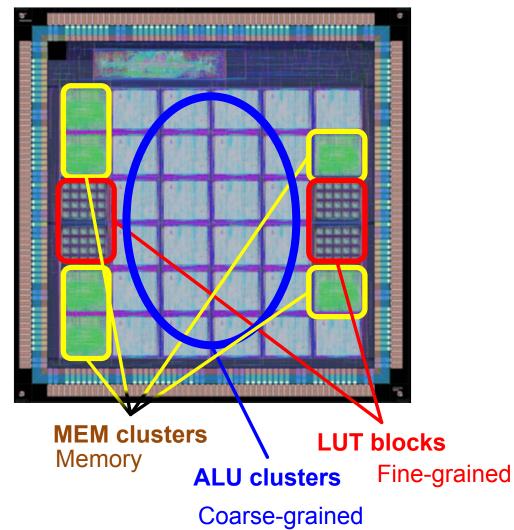
1S-7 Objective

Develop a mixed-grained reliability-variable reconfigurable array enabling C-based design

- Fine-grained elements for state machine
- **Coarse-grained** elements for data processing
- Element-wise configuration to cover various apps.

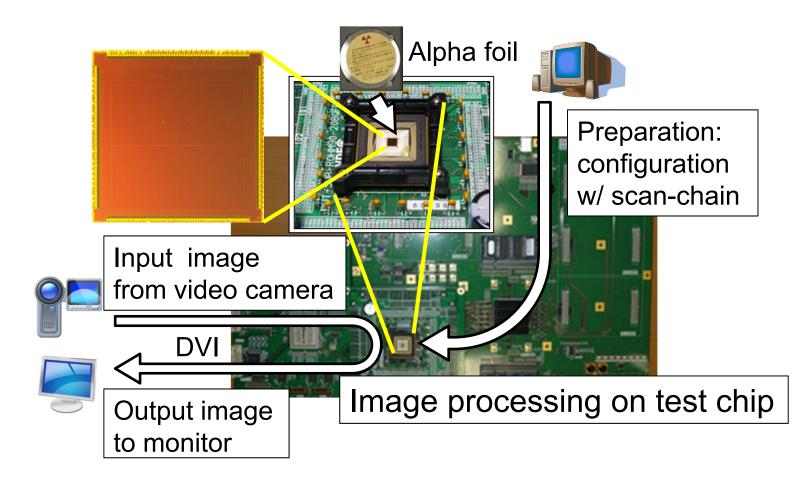


Process	65nm 12ML CMOS
Die size	4.2 x 4.2 mm ²
Config. bits	165,312
#gates	ALU: 120k, LUT: 4k, MEM: 99k

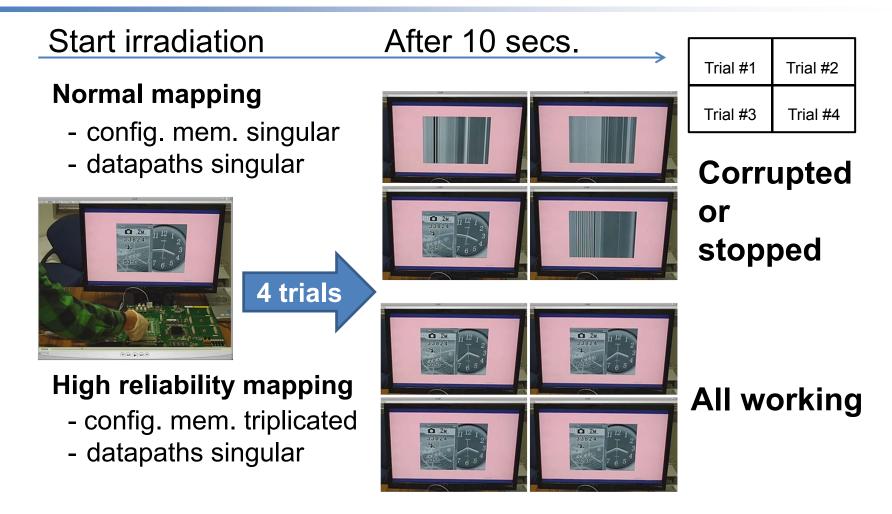


1S-7 Demonstration setup

To validate the functionality and reliability, a demonstration using two mappings with different reliability levels was performed.



1S-7 Demo: Alpha irradiation test



Single chip can cover wide reliability specifications with different mappings.